ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® Material Comp © Copyright 2005. 1 international and Pa	PC. Bannockt	ourn. Illinois. A	Il rights reserved u ntions.	nder both	This docum level parts,	ent is a declaratio the declaration en	n of the substanc compasses all lo	es within the manufactur wer level materials for w	er listed it hich the m	em. Note: if anufacturer	the item is an as has engineering	sembly with lowe responsibility.	
				Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information					on			
Supplier Information													
Company name* Company			npany unique ID			Unique ID Authority				Response Date*			
On Semiconductor										2020-06-01			
Contact Name Title - Contact			ct	t I		Phone - Contact*			Email - Contact*				
Product-Env-Stewards Product Envir			Enviro Compliance			NA			Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Repres			esentative		Phone - Representative*			Email - Representative*					
Product-Env-Stewards Produ			Product Enviro Compliance			NA			Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
	NCV770	NCV7708BDWR2G HALF BRID		DGE DRIVER		2020-06-01		PH1		92.01	mg	Each	
Manufacturing Proccess Informa	tion												
Terminal Plating / Grid Array M	Terminal Plating / Grid Array Material Terminal Base Alloy		Alloy J	-STD-020 MSI	L Rating	Peak Proces	s Body Tempera	ture Max Time at Peak	Temperat	ure Numbe	er of Reflow Cyc	eles	
Matte Tin (Sn) - annealed CU Alloy			3		260	С	30	secon	ds 3				
comments													
TTENTION: MSL 3 Rated item require	es Bake and D	ry Pack (after	electrical test)										
or more information regarding material	composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

sigma range of distribution unless otherwise noted).									
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure	
Die	29.61	mg	Supplier	Silicon (Si)	7440-21-3		29.61	mg	
Die Attach	12.56	mg	Supplier	Silver (Ag)	7440-22-4		9.42	mg	
			Supplier	Epoxy resins	129915-35-1		3.14	mg	
Lead Frame	196.75	mg	Supplier	Silver (Ag)	7440-22-4		6.4928	mg	
			Supplier	Zinc (Zn)	7440-66-6		0.3935	mg	
			Supplier	Iron (Fe)	7439-89-6		4.9188	mg	
			Supplier	Copper (Cu)	7440-50-8		184.945	mg	
Mold Compound-Black	545.87	mg		Epoxy Phenol Resin	proprietary		57.3163	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		488.5536	mg	
Plating	6.53	mg	Supplier	Tin (Sn)	7440-31-5		6.53	mg	
Wire Bond - Au	0.69	mg	Supplier	Gold (Au)	7440-57-5		0.69	mg	

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 signa range of distribution unless otherwise noted)